

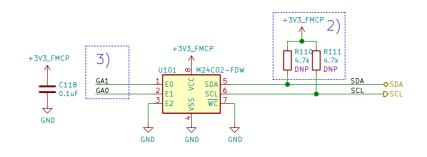
NOTES:

1) ZCU111 and ZCU216 have +3V3AUX connected to +3V3

2) I2C (SDA and SCL) is pulled up at the EVA Board to +3V3 3) VITA 57.1— Observation 5.22:

GA[0] is connected to Address bit [1] and GA[1] is connected to Address bit[0].
4) PG\_M2C signal is pulled up in VCU118

4) PG\_M2C signal is pulled up in VCU118
5) FPGA\_CLK needs capacitors in the mezzanine
6) DPCLKs have capacitors in the EVA Board



Mounting Holes

H101
 M2.5\_Pad
 M2.5
 M2.5
 M2.5
 M2.5
 M2.5

Fiducials

O FID101 O FID102 O FID103 Fiducial O Fiducial

O FID104 O FID105 O FID106 Fiducial

Heatsink

ink TestPoints

Heatsink

Luis Ardila
Institute for Data Processing and Electronics (IPE)

Karlsruhe Institute of Technology (KIT)

Sheet: /
File: fmcp\_sma.sch

File: fmcp\_sma.sch

Title: QSolid FMC+ SMA breakout

 Size: A2
 Date: 2022-11-30
 Rev: 1.0

 KiCad E.D.A. kicad 5.1.12-84ad8e8a8692ubuntu18.04.1
 Id: 1/1